

ABSTRACT OF THE DISCLOSURE

The number of recognition operations for the circuit-formed substrate (14) as a whole is reduced by concurrently recognizing a bad mark (23) and an individual substrate mark (22) in the course of a recognition process of a single or a plurality of individual substrate(s) (16) provided by sectioning the circuit-formed substrate (14). The results of the recognition of the inclination and dislocation of the circuit-formed substrate (14) are used to control the position of the substrate-recognition camera (15) which recognizes the individual substrate (15), thereby reducing the rate of occurrence of recognition errors. When a component of the recognition marks (21) or (22) is captured within the visual field (31) of the substrate-recognition camera (15), the position of the recognized marks (21) or (22) is specified, and such a mark is again recognized, and thus, the occurrence of recognition error can be inhibited.